

Title:	Process Change Notification/Request		
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WanTcom Product Model:

WHM0006AE, WHM0010AE, WHM0013AE, WHM0015AE, WHM005-15AE, WHM0002AE, WHM0104AE, WHM04-2045AE, and WHM0715AE

Effective Lots: Starting from lot 1525.

1. Reason:

In order to have better thermal conductivity and no solder residue on the back of these 1 Watt modules, all the vias on the substrate are filled with Silver based high conductive epoxy before the Gold plating.

2. Change Detail:

- a) Before the change, Fig. 1 shows the bottom of the module. The solder filled via caused spreading solder and some of the vias may not be fully filled.



Figure 1 Before the process change



Figure 2 New process of via filled

- b) Fig. 2 illustrates the bottom view of the new via filled substrate. All the vias are filled with the high conductive Silver epoxy after the Copper plating but before the final Gold plating. The solid filled vias provide better thermal conductivity than that of the previous solder filled process and also very clean surface.

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